

Hydrogen; Helium; Xenon; Nitrogen; Hydrogen Chloride; Sulfuric Acid; Nitric Acid; Phosphoric Acid; Hydrofluoric Acid; Silicate reagent; Hydrogen Bromide; Carbon dioxide; Silica; Carbon Monoxide; Nitrous Oxide; Nitric Oxide; Sulfur dioxide; Boron trichloride; Dichlorosilane; Silane; Silicon tetrachloride; Chlorine trifluoride; Diiodosilane; Nitrogen trifluoride; Anhydrous ammonia; Potassium Hydroxide in solid form; Sulfur hexafluoride gas; Tungsten hexafluoride; Titanium tetrachloride; Carbonyl sulfide; Copper sulphate solution; Potassium chloride electrode filling solution; Cerium hydroxide; Hydrogen peroxide; Disilane; Phosphine of copper; Octane; Ethyne aka Acetylene; Trifluoromethane; Halocarbon; Difluoromethane; Fluoromethane; Octafluorocyclobutane; Isopropyl alcohol; Tert-butyl alcohol; Hexachlorodisilane; 2-Heptanone; Cyclohexanone; Cyclopentanone; Sodium acetate; Butyl acetate; Propylene glycol monomethyl ether acetate; 2-(Methylamino)ethanol; Tetramethylammonium hydroxide; Tetraethylsilanedi-amine; Di-isopropylaminosilane; Tetramethylsilane; Trimethylaluminum; Trimethylsilane; Butyrolactone; Potassium chloride; Butoxyethanol; Ethanolamine; Lubrication containing 50% or more by weight of petroleum oils; Ammonium; Cerium dioxide; Tetraethylammonium hydroxide; Welding powder; Triethanolamine based solution; Dimethyl sulfoxide; Wafers polycrystalline silicon; Cobalt based solution; Diborane gas; Ethylene glycol based solution; Ion exchanger resin; Ammonium fluoride; Glass Rods; Permanent metal magnets; Central Processing Unit; Memory—Dynamic Random-Access Memory; Cobalt sputtering target; Copper sputtering target; Deuterium; Hydrocarbon deposition solution; Tantalum powder; Tetrakis (methylenehydrazine) zirconium; 2-Propanol, 1-methoxy, 2-acetate based undercoat material; Polyglycerol polymer based slurry; Surfactant solution; Hydroxyethanediphosphonic acid based wafer cleaning solution; Acetic acid based slurry; Amorphous silica based slurry; Silica and phosphoric acid based slurry; 4-Morpholinecarbaldehyde based solution; Nitrogen trifluoride; Benzotriazole based cleaning solution; Helium and nitrogen mixture; Helium based compressed gas mixture; Hydrogen and argon mixture; Isobutyl propionate-based developer solution; Methane and argon mixture; and

Oxygen and helium mixture (duty rate ranges from duty-free to 6.5%).

The request indicates that certain materials/components are subject to duties under section 122 of the Trade Act of 1974 (Section 122), section 232 of the Trade Expansion Act of 1962 (section 232), or section 301 of the Trade Act of 1974 (section 301), depending on the country of origin. The applicable section 122, section 232, and section 301 decisions require subject merchandise to be admitted to FTZs in privileged foreign status (19 CFR 146.41).

Public comment is invited from interested parties. Submissions shall be addressed to the Board's Executive Secretary and sent to: ftz@trade.gov. The closing period for their receipt is September 2, 2026.

A copy of the notification will be available for public inspection in the "Online FTZ Information System" section of the Board's website.

For further information, contact John Frye at John.Frye@trade.gov.

Dated: July 22, 2026.

Elizabeth Whiteman,
Executive Secretary.

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DEPARTMENT OF COMMERCE

Foreign-Trade Zones Board

[B–35–2025]

Foreign-Trade Zone (FTZ) 38; Authorization of Limited Production Activity; GE Gas Turbines (Greenville) LLC; (Gas Turbines); Greenville, SC

On June 30, 2025, GE Gas Turbines (Greenville) LLC submitted a notification of proposed production activity to the FTZ Board for its facility within FTZ 38, in Greenville, South Carolina.

The notification was processed in accordance with the regulations of the FTZ Board (15 CFR part 400), including notice in the **Federal Register** inviting public comment (90 FR 30047–30048, July 8, 2025). On July 17, 2026, the applicant was notified of the FTZ Board's decision that further review of part of the proposed activity is warranted. The FTZ Board authorized the production activity described in the notification on a limited basis, subject to the FTZ Act and the Board's regulations, including section 400.14, and further subject to a restriction requiring entry and duty payment on any steel, aluminum or derivative components unless eligible for drawback under the

effective Section 232 proclamations at the time of entry.

Dated: July 17, 2026.

Elizabeth Whiteman,
Executive Secretary.

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DEPARTMENT OF COMMERCE

Foreign-Trade Zones Board

[B–28–2025]

Foreign-Trade Zone (FTZ) 173; Authorization of Limited Production Activity; PINNACLEMOD LLC; (Prefabricated Modular Steel Buildings); Aberdeen, Washington

On May 13, 2025, PINNACLEMOD LLC submitted a notification of proposed production activity to the FTZ Board for its facility within FTZ 173, in Aberdeen, Washington.

The notification was processed in accordance with the regulations of the FTZ Board (15 CFR part 400), including notice in the **Federal Register** inviting public comment (90 FR 21737–21738, May 21, 2025). On July 17, 2026, the applicant was notified of the FTZ Board's decision that further review of part of the proposed activity is warranted. The FTZ Board authorized the production activity described in the notification on a limited basis, subject to the FTZ Act and the Board's regulations, including section 400.14, and further subject to a restriction requiring that wood flooring and wood doors currently classified under HTSUS Chapter 44 be admitted into the FTZ in privileged foreign (19 CFR 146.41) status and further subject to a restriction requiring entry and duty payment on any steel, aluminum or derivative components unless eligible for drawback under the effective Section 232 proclamations at the time of entry.

Dated: July 17, 2026.

Elizabeth Whiteman,
Executive Secretary.

[FR Doc. 2026–14968 Filed 7–23–26; 8:45 am]

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